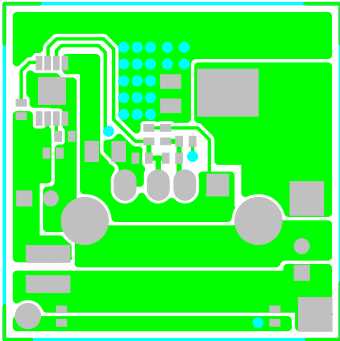
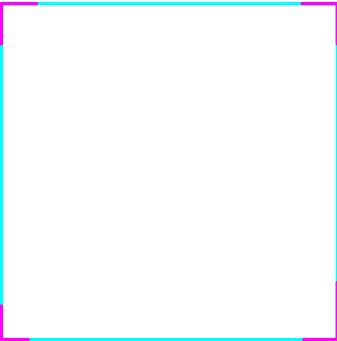


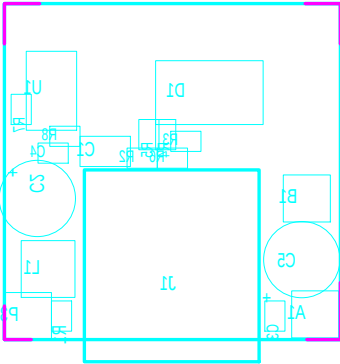
TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP8286_SEC		Rev. C	L1										
Date: {Start Date}	Filename: PMP8386_SEC_REVC.PCB	Engineer: B.KING	PCB Dsgnr: B.KING		Modified Date: {Modification Date}						Software	PADs v9.3	



TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP8286_SEC		Rev. C		L2									
Date: {Start Date}	Filename: PMP8386_SEC_REVC.PCB	Engineer: B.KING	PCB Dsgnr: B.KING		Modified Date: {Modification Date}					Software	PADs v9.3		



TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP8286_SEC		Rev. C	L1								TA		
Date: {Start Date}	Filename: PMP8386_SEC_REVC.PCB	Engineer: B.KING	PCB Dsgnr: B.KING		Modified Date: {Modification Date}						Software PADs v9.3		



TEXAS INSTRUMENTS			Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
			Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP8286_SEC		Rev. C		L2								BA	
Date: {Start Date}	Filename: PMP8386_SEC_REVC.PCB	Engineer: B.KING	PCB Dsgnr: B.KING		Modified Date: {Modification Date}						Software	PADs v9.3	

PLEASE NOTICE BOARD THICKNESS



FABRICATION CHART			
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
<input checked="" type="checkbox"/> 0.025 <input type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 2 <input type="checkbox"/> NONE	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT
<input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX	<input checked="" type="checkbox"/> 0.010/0.010 <input type="checkbox"/> 0.008/0.007 <input type="checkbox"/> 0.006/0.006		<input type="checkbox"/> SINGLE SIDED <input checked="" type="checkbox"/> 2 LAYER <input type="checkbox"/> 4 LAYER <input type="checkbox"/> OTHER _____

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR
2. BASE LAMINATE:

EQUIVALENT, W/Tg ≈140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK:

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES:

UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING:

HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH:

PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND:

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS:

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP:

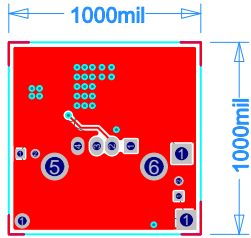
BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION:

PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES:

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER:

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES:

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. PMP8286_SEC		Rev. C		L1								FB
Date: (Start Date)	Filename: PMP8386_SEC_REV.C.PCB	Engineer: B.KING		PCB Designer: B.KING		Modified Date: (Modification Date)					Software: PADS v9.3	

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